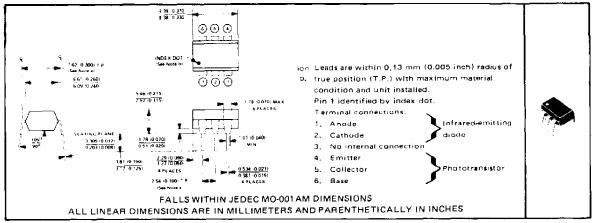
COMPATIBLE WITH STANDARD TTL INTEGRATED CIRCUITS

- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Phototransistor
- High Direct-Current Transfer Ratio
- High-Voltage Electrical Isolation . . . 5000-V Rating
- Plastic Dual-In-Line Package
- High-Speed Switching: $t_r = 2 \mu s$, $t_f = 2 \mu s$ Typical
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays, and Pulse Transformers

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

| Input-to-Output Voltage | | | | | | | |
|---|----------------|------|------|------|---|------|--------|
| Collector-Base Voltage | | | | | | | |
| Collector-Emitter Voltage (See Note 1) | | | | | - | | . 30 ' |
| Emitter-Collector Voltage | | | | | | | 7 |
| Emitter Base Voltage | | | | | | | |
| Input-Diode Reverse Voltage | | | | | | | |
| Input-Diode Continuous Forward Current | | | | | | | |
| Continuous Power Dissipation at (or below) 25°C | | | | | | | |
| Infrared-Emitting Diode (See Note 2) | | | | | | | 150 m |
| Phototransistor (See Note 3) | | | | | | | |
| Total, Infrared-Emitting Diode plus Phototran | | | | | | | |
| Storage Temperature Range | | | | | | | |
| | for 10 Seconds | | | | | | 260 |

NOTES 1. This value applies when the base emitter diode is open-circuited.

- 2. Derate linearly to 100 °C free air temperature at the rate of 2 mW/ °C.
- 3. Denate linearly to 100 $^{\circ}$ C free-air temperature at the rate of 2 mW/ C. .
- 4. Denote linearly to 100 C free-air temperature at the rate of 3.33 mW/ $^{\prime}C_{*}$

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1

TIL124, TIL125, TIL126 Optocouplers

| PARAMETER | | | | TIL124 | | | TIL 125 | | | TIL126 | | | [|
|--|--|----------------------------------|---|--------|------|-----|---------|------|-----|--------|------|-----|------|
| | | | TEST CONDITIONS | MIN | TYP | MAX | MIN | TYP | MAX | MIN | TYP | ΜΑΧ | UNIT |
| Collector-Base V(BR)C80 Breakdown Voltage | | Ic = 10 µA, IE = 0. IF = 0 | 70 | | | 70 | | | 70 | | | v | |
| VIBR)CEO | Collector Breakdow | -Emitter vn Voltage | l <u>c</u> =1mA, l <u>g</u> ≃0, l _F ≂0 | 30 | | | 30 | | | 30 | | | v |
| Emitter-Base VIBR)EBO Breakdown Voltage | | - | $I_{E} = 10 \mu A$, $I_{C} = 0$, $I_{F} = 0$ | 7 | | | 7 | | | 7 | | | v |
| Input Diode Static | | | VR = 3 V | | | 10 | | | 10 | | | 10 | μA |
| ¹ C(an) | On-State Collector | Phototransistor Operation | VCE = 10 V, IF = 10 mA, IB = 0 | 1 | 3 | | 2 | 5 | | 5 | 9 | | mΑ |
| | Current | Photodiode Operation | V _{CB} = 10 V, I _F = 10 mA, I _E = 0 | 5 | 20 | | 5 | 20 | | 5 | 20 | | Αų |
| ^I C(off) | Off-State Collector Current | Phototransistor Operation | V _{CE} = 10 V, I _F ≤ 0 I _B = 0 | | 1 | 50 | | 1 | 50 | | 1 | 50 | nA |
| | | Photodiode Operation | V _{CB} = 10 V, i _F = 0, i _E = 0 | | 0.1 | 20 | | 0.1 | 20 | | 0.1 | 20 | |
| Transistor Static NEE Forward Current Transfer Ratio | | VCE = 5 V, IC = 10 mA, i⊭ = 0 | 50 | 100 | | 100 | 200 | | 100 | 550 | | | |
| V _F F Forward Voltage | | | IF ≈ 10 mA | | 1.2 | 1,4 | | 1.2 | 1,4 | | 1.2 | 1.4 | v |
| VCE(sat) | Collector-Emitter E(sat) Saturation Voltage | | 1 _C = 1 mA, I _F = 10 mA, I _B = 0 | | 0.25 | 0.4 | | 0,25 | 0.4 | | 0.25 | 0.4 | v |
| rio | Input-to-Output Internal Resistance | | Vin-out = 500 V, See Note 5 | 10'' | | | 10'' | | | 1011 | | | Ω |
| Cia | Input-to-C | • | Vin-out = 0, f = 1 MHz, See Note 5 | | 1 | 1.3 | | 1 | 1.3 | | 1 | 1.3 | pF |

electrical characteristics at 25°C free-air temperature

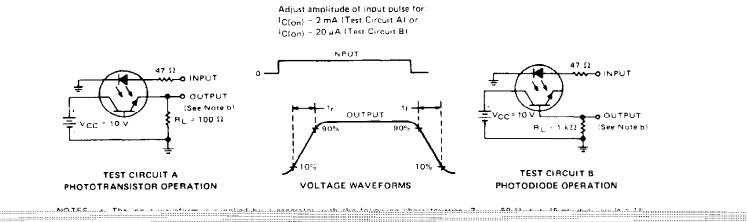
NOTE 5: These parameters are measured between both input diode leads shorted together and all the phototransistor leads shorted together.

switching characteristics at 25°C free-air temperature

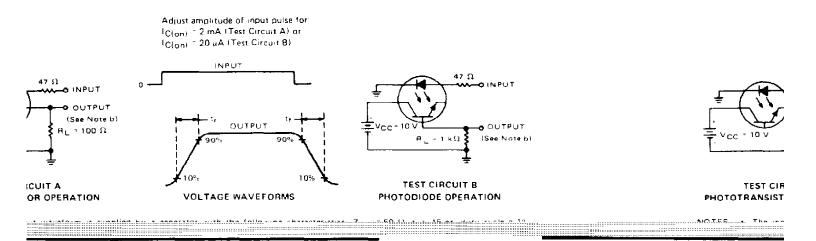
| | PARA | METER | TEST CONDITIONS | MIN | TYP | ΜΑΧ | UNIT |
|----------------|-----------|-----------------|---|-----|-----|-----|------|
| t, | Rise Time | Phototransistor | $V_{CC} = 10 V$, $I_{C(on)} = 2 mA_{RL} = 100 \Omega$, | | 5 | 10 | |
| ч | Fall Time | Operation | See Test Circuit A of Figure 1 | | 5 | 10 | μs |
| t _r | Rise Time | Photodiode | $V_{CC} = 10 V$, $I_{C(on)} = 20 \mu A_{RL} = 1 k\Omega$. | | 1 | | |
| t _f | Fall Time | Operation | See Test Circuit B of Figure 1 | | 1 | | 211 |

TIL124, TIL125, TIL126 **OPTOCOUPLERS**

PARAMETER MEASUREMENT INFORMATION

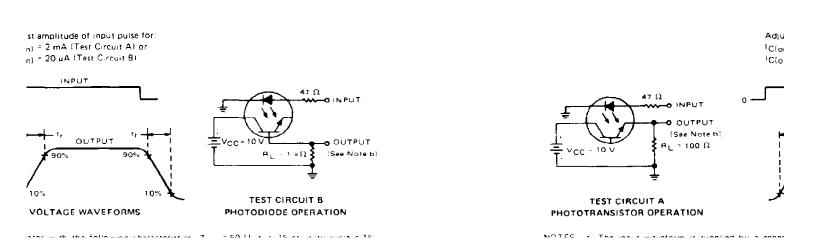




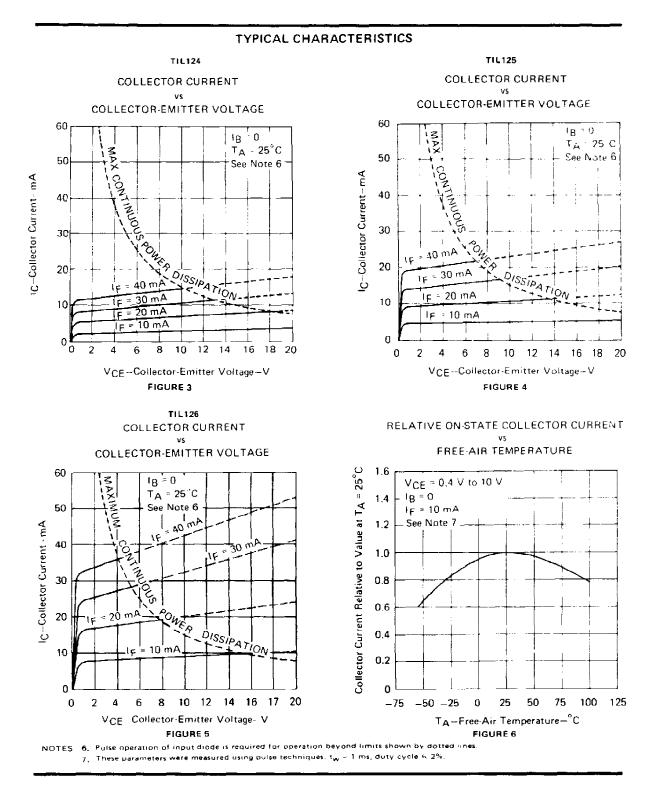


I MEASUREMENT INFORMATION

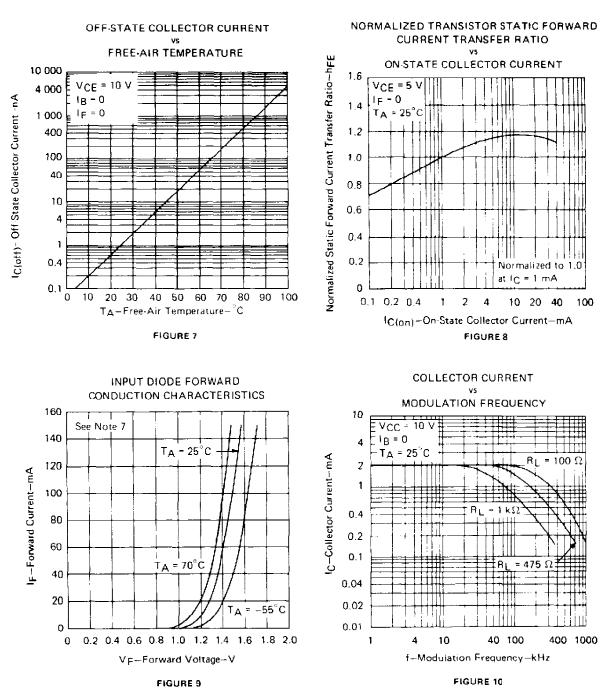
PARAMETER



TIL124, TIL125, TIL126 OPTOCOUPLERS







TYPICAL CHARACTERISTICS

NOTE 7: These parameters were measured using pulse techniques, t_{vv} = 1 ms, duty cycle \leqslant 2%.



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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|---------------------|-------------------------|------------------|------------------------------|
| TIL124 | OBSOLETE | PDIP | Ν | 6 | TBD | Call TI | Call TI |
| TIL125 | OBSOLETE | PDIP | Ν | 6 | TBD | Call TI | Call TI |
| TIL126 | OBSOLETE | PDIP | Ν | 6 | TBD | Call TI | Call TI |

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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